National Semiconductor

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MM54HCT109/MM74HCT109
Dual J-$\overline{K}$ Flip-Flops with Preset and Clear

General Description

These high speed J-$\overline{K}$ FLIP-FLOPS utilize advanced silicon-gate CMOS technology. They possess the low power consumption and high noise immunity of standard CMOS integrated circuits, along with the ability to drive 10 LS-TTL loads.

Each flip flop has independent J, $\overline{K}$, PRESET, CLEAR, and CLOCK inputs and Q and $\overline{Q}$ outputs. These devices are edge sensitive to the clock input and change state on the positive going transition of the clock pulse. Clear and preset are independent of the clock and accomplished by a low logic level on the corresponding input.

The 54HCT/74HCT logic family is functionally as well as pin-out compatible with the standard 54LS/74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

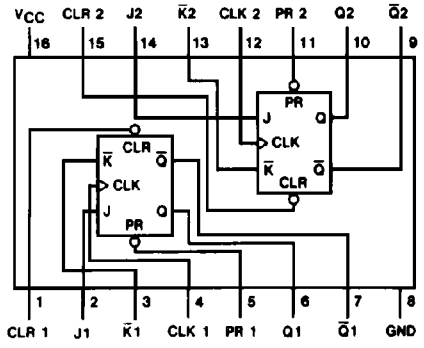
MM54HCT/MM74HCT devices are intended to interface between TTL and NMOS components and standard CMOS devices. These parts are also plug-in replacements for LS-TTL devices and can be used to reduce power consumption in existing designs.

Features

- Typical propagation delay: 20 ns
- Low input current: 1 μA maximum
- Low quiescent current: 40 μA maximum (74HCT Series)
- Output drive capability: 10 LS-TTL loads

Connection and Logic Diagrams

Dual-In-Line Package



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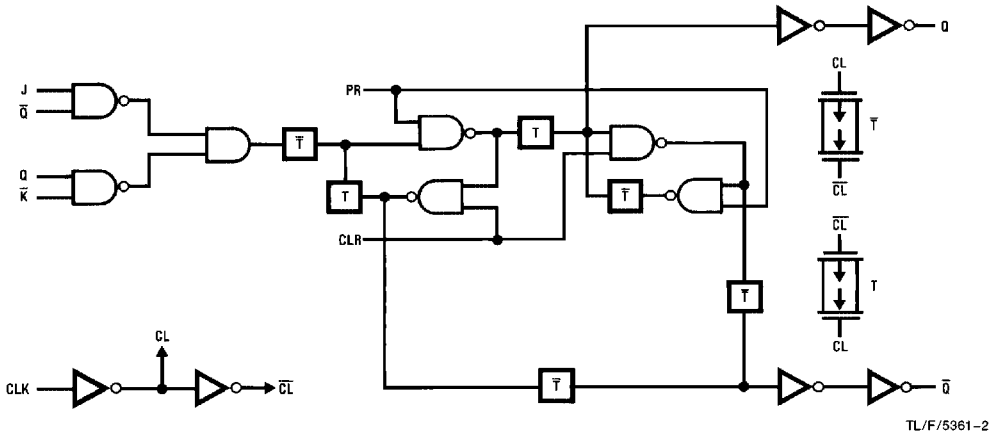
Function Table

Inputs					Outputs	
PR	CLR	CLK	J	$\overline{K}$	Q	$\overline{Q}$
L	H	X	X	X	H	L
H	L	X	X	X	L	H
L	L	X	X	X	H*	H*
H	H	↑	L	L	L	H
H	H	↑	H	L	TOGGLE	
H	H	↑	L	H	Q0	$\overline{Q}$0
H	H	↑	H	H	H	L
H	H	L	X	X	Q0	$\overline{Q}$0

Order Number MM54HCT109 or MM74HCT109



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Absolute Maximum Ratings (Notes 1 & 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage (V_{CC})	−0.5 to +7.0V
DC Input Voltage (V_{IN})	−1.5 to V_{CC} +1.5V
DC Output Voltage (V_{OUT})	−0.5 to V_{CC} +0.5V
Clamp Diode Current (I_{IK}, I_{OK})	±20 mA
DC Output Current, per pin (I_{OUT})	±25 mA
DC V_{CC} or GND Current, per pin (I_{CC})	±50 mA
Storage Temperature Range (T_{STG})	−65°C to +150°C
Power Dissipation (P_D) (Note 3)	600 mW
S.O. Package only	500 mW
Lead Temperature (T_L) (Soldering 10 seconds)	260°C

Operating Conditions

	Min	Max	Units
Supply Voltage (V_{CC})	4.5	5.5	V
DC Input or Output Voltage (V_{IN}, V_{OUT})	0	V_{CC}	V
Operating Temp. Range (T_A)			
MM74HCT	−40	+85	°C
MM54HCT	−55	+125	°C
Input Rise or Fall Times (t_r, t_f)		500	ns

DC Electrical Characteristics V_{CC} = 5V ±10% (unless otherwise specified)

Symbol	Parameter	Conditions	T_A = 25°C	74HCT T_A = −40 to 85°C	54HCT T_A = −55 to 125°C	Units
			Typ	Guaranteed Limits		
V_{IH}	Minimum High Level Input Voltage			2.0	2.0	2.0	V
V_{IL}	Maximum Low Level Input Voltage			0.8	0.8	0.8	V
V_{OH}	Minimum High Level Output Voltage	V_{IN} = V_{IH} or V_{IL}					
		$\|I_{OUT}\|$ = 20 μA	V_{CC}	V_{CC} − 0.1	V_{CC} − 0.1	V_{CC} − 0.1	V
		$\|I_{OUT}\|$ = 4.0 mA, V_{CC} = 4.5V	4.2	3.98	3.84	3.7	V
		$\|I_{OUT}\|$ = 4.8 mA, V_{CC} = 5.5V	5.2	4.98	4.84	4.7	V
V_{OL}	Maximum Low Level Voltage	V_{IN} = V_{IH} or V_{IL}					
		$\|I_{OUT}\|$ = 20 μA	0	0.1	0.1	0.1	V
		$\|I_{OUT}\|$ = 4.0 mA, V_{CC} = 4.5V	0.2	0.26	0.33	0.4	V
		$\|I_{OUT}\|$ = 4.8 mA, V_{CC} = 5.5V	0.2	0.26	0.33	0.4	V
I_{IN}	Maximum Input Current	V_{IN} = V_{CC} or GND, V_{IH} or V_{IL}		±0.1	±1.0	±1.0	μA
I_{CC}	Maximum Quiescent Supply Current	V_{IN} = V_{CC} or GND I_{OUT} = 0 μA		4.0	40	80	μA
		V_{IN} = 2.4V or 0.5V (Note 4)		0.3	0.4	0.5	mA

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: −12 mW/°C from 65°C to 85°C; ceramic "J" package: −12 mW/°C from 100°C to 125°C.

Note 4: Measured per pin, all other inputs held at V_{CC} or GND.

AC Electrical Characteristics $V_{CC}=5V$, $T_A=25°C$, $C_L=15$ pF, $t_r=t_f=6$ ns

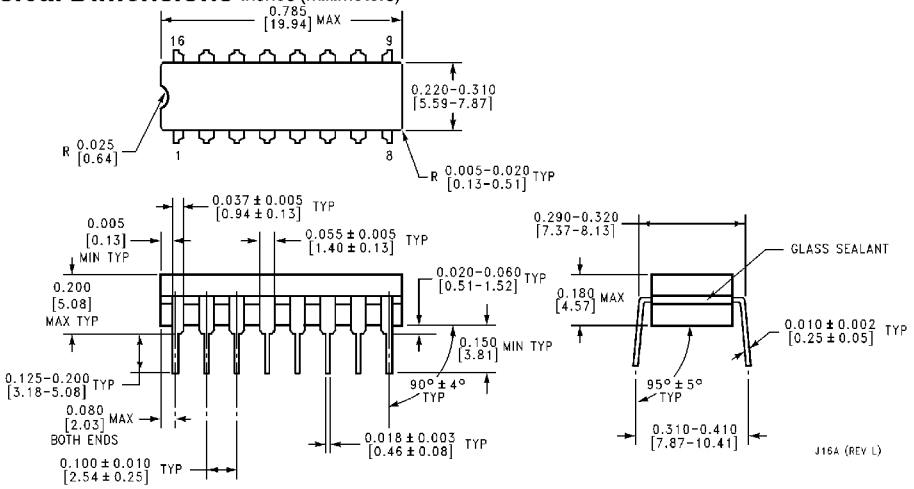
Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
f_{MAX}	Maximum Operating Frequency		50	30	MHz
t_{PHL}, t_{PLH}	Maximum Propagation Delay from Clock to Q or $\overline{Q}$		18	30	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay from Preset or Clear to Q or $\overline{Q}$		18	30	ns
t_{REM}	Minimum Removal Time, Preset or Clear to Clock			20	ns
t_S	Minimum Setup Time J or $\overline{K}$ Clock		10	20	ns
t_H	Minimum Hold Time Clock to J or $\overline{K}$		−3	0	ns
t_W	Minimum Pulse Width Clock, Preset or Clear		8	16	ns

AC Electrical Characteristics $V_{CC}=5.0V \pm 10\%$, $C_L=50$ pF, $t_r=t_f=6$ ns (unless otherwise specified)

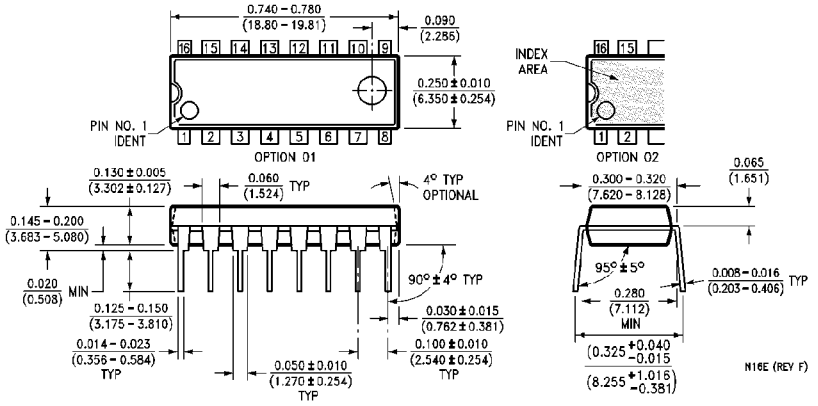
Symbol	Parameter	Conditions	$T_A=25°C$	74HCT $T_A=-40°$ to $85°C$	54HCT $T_A=-55°$ to $125°C$	Units
			Typ	Guaranteed Limits		
f_{MAX}	Maximum Operating Frequency			27	22	18	MHz
t_{PHL}, t_{PLH}	Maximum Propagation Delay from Clock to Q or $\overline{Q}$		22	35	44	52	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay from Preset or Clear to Q or $\overline{Q}$		22	35	44	52	ns
t_{REM}	Minimum Removal Time Preset or Clear to Clock			20	25	30	ns
t_S	Minimum Setup Time J or $\overline{K}$ to Clock		10	20	25	30	ns
t_H	Minimum Hold Time Clock to J or $\overline{K}$		−3	0	0	0	ns
t_W	Minimum Pulse Width Clock, Preset or Clear			16	20	24	ns
t_r, t_f	Maximum Input Rise and Fall Time			500	500	500	ns
t_{THL}, t_{TLH}	Maximum Output Rise and Fall Time			15	19	22	ns
C_{PD}	Power Dissipation Capacitance (Note 5)	(per flip-flop)	35				pF
C_{IN}	Maximum Input Capacitance		5	10	10	10	pF

Note 5: C_{PD} determines the no load dynamic power consumption, $P_D=C_{PD}\ V_{CC}^2\ f+I_{CC}\ V_{CC}$, and the no load dynamic current consumption, $I_S=C_{PD}\ V_{CC}\ f+I_{CC}$.

Physical Dimensions inches (millimeters)



Order Number MM54HCT109J or MM74HCT109J
NS Package J16A



Order Number MM74HCT109N
NS Package N16E

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